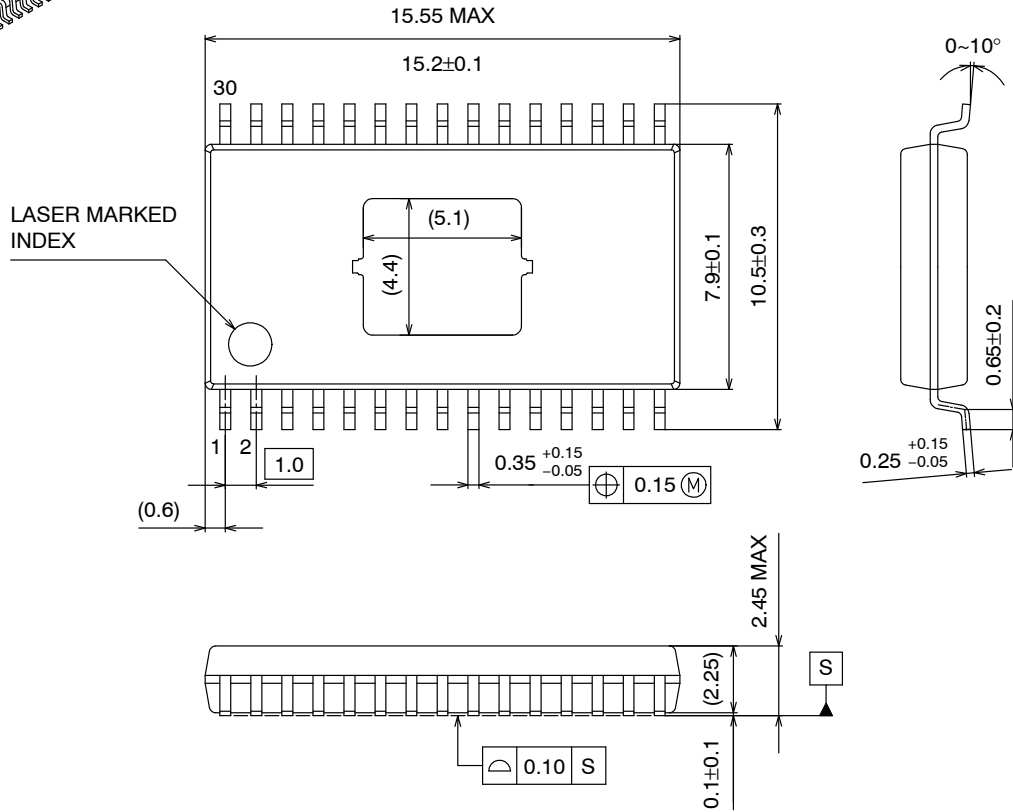
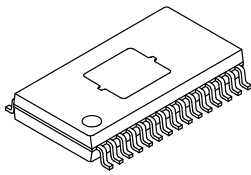


MECHANICAL CASE OUTLINE

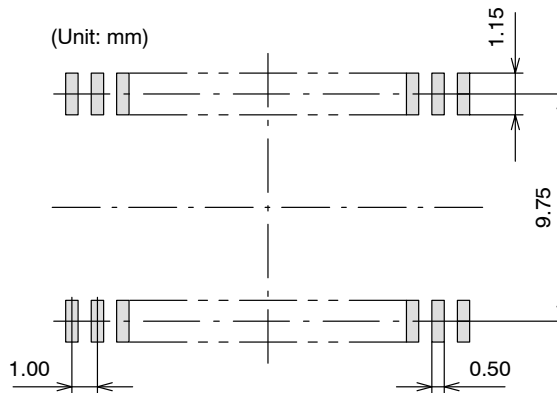
PACKAGE DIMENSIONS

SOIC30 W / MFP30KR (375 mil)
CASE 751CH
ISSUE A

DATE 08 NOV 2013




SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOIC30 W / MFP30KR (375 MIL)	PAGE 1 OF 1

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